

Effect of Phonon Boundary Scattering on Seebeck Coefficient in Silicon Thin Films

Osaka Univ.*, Shizuoka Univ.**

○Indra Nur Adisusilo*, Faiz Salleh**, Hiroya Ikeda**, Yoshinari Kamakura*

E-mail: indra@si.eei.eng.osaka-u.ac.jp

Introduction: Seebeck coefficient S has two components, the diffusive and the phonon-drag part [1]. Recently, Salleh et al. measured S in SOI thin films [2] and found that the film thickness ($t_{\text{Si}} = 9 - 100$ nm) has little impact on the phonon-drag component (see, Fig. 1), which is considered to be proportional to phonon mean free path λ [3]. On the other hand, the experimental observation of the thermal conductivity κ suggests that λ is significantly shortened in ultrathin films by the frequent boundary scattering. Here in our investigation we suspect the effect of specularity in boundary scattering as the cause of this inconsistency.

Method: Specularity in phonon boundary scattering is expressed as $p = \exp(-4\eta^2 k^2)$, where η is the surface roughness RMS and k the phonon wavenumber [4]. Considering the phonons which participate in intravalley electron-phonon scattering in Si, the typical wavenumber of phonons which mainly contribute to the phonon drag can be estimated to be $k_{\text{pd}} \sim 4 \times 10^6 \text{ cm}^{-1}$. Thus, the value of p relevant to this wavenumber can be obtained from Fig. 2. Then, we calculated λ by considering the phonon scattering mechanisms (Umklapp and normal scattering) as well as the boundary scattering whose relaxation time is expressed as $\tau_B = (L/v)[(1+p)/(1-p)]$, where L is the Casimir length and v the sound velocity [5].

Discussion: In Fig. 2 we can see that Si films with $\eta = 0.2$ nm [6] has p of 0.9 at the wavenumber relevant to the phonon-drag contribution. This yields λ to be less affected by the thickness of Si film, as can be seen in Fig. 3. In contrast, phonons which mainly contributes to κ usually has higher wavenumbers ($k_{\text{tc}} \sim 4 \times 10^7 \text{ cm}^{-1}$ @ 300 K [5]), yielding $p \approx 0$ (i.e. diffusive transport) and thus κ is sensitive to changes in film thickness. This difference is thought to be the cause as of why Seebeck coefficient in Si films seemed to be unaffected by the thickness.

Acknowledgement: This work was partially supported by the Murata Science Foundation.

References: [1] M. W. Wu et al., Phys. Rev. B 54, 5438 (1996). [2] F. Salleh et. al., J. Appl. Phys. **105**, 102104 (2014). [3] E. Behnen, J. Appl. Phys. **67**, 287 (1990). [4] J. M. Ziman, *Electrons and Phonons* (Clarendon Press, Oxford, 1960). [5] X. Wang et. al., Sci. Rep. **4**, 6399 (2014). [6] K. Reinhardt et. al. (ed), *Handbook of Silicon Wafer Cleaning Technology, 2nd Ed.* (William Andrew, New York, 2008). [7] T. H. Geballe et al., Phys. Rev. 98, 4 (1955).

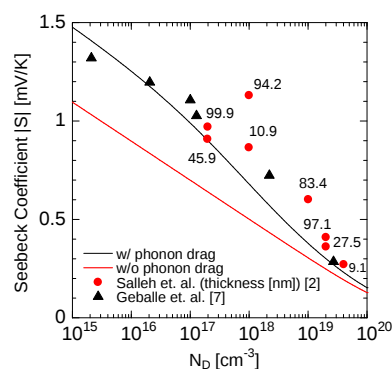


Fig. 1. Seebeck coefficient of Si thin film with various thicknesses (red dots) and bulk silicon (black triangles). Lines shows analytical values for S with phonon-drag (red line), and without phonon-drag (black line). It can be seen that thin films and bulk have similar values of S .

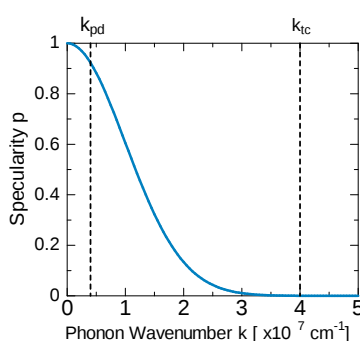


Fig. 2. The estimated specularity of boundary scattering when the surface roughness RMS of $\eta = 0.2$ nm (blue line). Black dashed line shows the typical wavenumber of phonons which contributes in intravalley electron-phonon scattering (k_{pd}) and those contributes in thermal transport (k_{tc}).

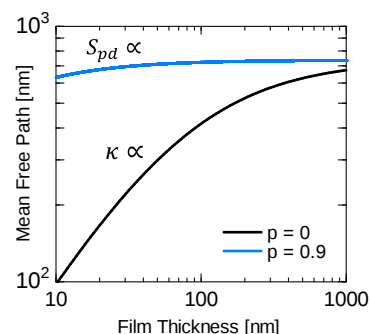


Fig. 3. Mean free path obtained using the specularity value of phonons with wavenumber k_{pd} (see Fig. 2) for $\eta = 0.2$ nm (blue line). Black line shows mean free path when boundary scattering is fully diffusive, which corresponds to (k_{tc}).